SH&W Dkt No: P01, 0144 Siemens Corp. Dkt. No: 2001 P 07506 US

## DECLARATION FOR PATENT APPLICATION, POWER OF ATTORNEY & DESIGNATION OF CORRESPONDENCE ADDRESS

As below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name, Leo M. HIGGINS, III.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

## METHOD AND STRUCTURE OF IN-SITU WAFER SCALE POLYMER STUD GRID ARRAY CONTACT FORMATION

# CLAIM FOR BENEFIT OF PRIOR U.S. PROVISIONAL APPLICATION(S) (34 U.S.C. § 119(e))

Day/Month/Year Filed

1290769212

Prior Foreign Application(s)

Country

I hereby claim the benefit under Title 35, United States Code, § 119(3) of any United States provisional application(s) listed below:

Priority Claimed

Yes

No

Number

the specification of which (check one)

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Provisional Application Number 60/272,520	Filing Date
00/2/2,520	March 1, 2001

# CLAIM FOR BENEFIT OF EARLIER US/PCT APPLICATION(S) UNDER 35 U.S.C. 120

I hereby claim the benefits under 35 USC §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of 35 USC §112, I acknowledge the duty to disclose material information as defined in 37 CFR §1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

Appl. No.	Filing Date	Patented, Pending, Abandoned

Power of Attorney: As a named inventor, I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and transact all business in the United States Patent and Trademark Office connected therewith: Adel A. Ahmed, Reg. No. 29,606; I. Marc Asperas, Reg. No. 37,274; Alexander J. Burke, Reg. No. 40,425; Joseph S. Codispoti, Reg. No. 31,819; Tracy L. Hurt, Reg. No. 34,188; Mark H. Jay, Reg. No. 27,507; Brian K. Johnson, Reg. No. 46,808; Stuart P. Kaler, Reg. No. 35,913; Rosa S. Kim, Reg. No. 39,728; Peter A. Luccarelli Jr., Reg. No. 29,750; James M. Markarian, Reg. No. 31,277; Frank G. Montgomery, Reg. No. 41,202; Jeffrey P. Morris, Reg. No. 25,307; Pasquale Musacchio, Reg. No. 36,876; John Musone, Reg. No. 44,961; Frank J. Nuzzi,, Reg. No. 44,310 Laura M. Slenzak, Reg. No. 35,363; Daniel J. Staudt, Reg. No. 34,733; Erik C. Swanson, Reg. No. 40,194; Heather S. Vance, Reg. No. 39,033; Michael J. Wallace, Reg. No. 44,486.

#### Send Correspondence to:

Elsa Keller, Legal Assistant Intellectual Property Department SIEMENS CORPORATION 186 Wood Avenue South Iselin, New Jersey 08830 Tel. No. (732) 321-3026

I hereby declare that all statements made herein on my own knowledge are true and that all statements made on information and belief are believed to be true, and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both under 18 USC §1001 and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

SH&W Dkt No: P01, 0144 Siemens Corp. Dkt. No: 2001 P 07506 US

Date: /

Leo M. HIGGINS, III

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